

# SS22, SS24

## Surface Mount Schottky Power Rectifier SMB Power Surface Mount Package

... employing the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over-Voltage Protection
- Low Forward Voltage Drop

### Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL94, VO at 1/8"
- Weight: 95 mg (approximately)
- Cathode Polarity Band
- Lead and Mounting Surface Temperature for Soldering Purposes:  
260°C Max. for 10 Seconds
- Available in 12 mm Tape, 2500 Units per 13" Reel, Add "T3" Suffix to Part Number
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- ESD Ratings: Machine Model = C  
Human Body Model = 3B

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	20 40	V
Average Rectified Forward Current (At Rated $V_R$ , $T_L = 100^\circ\text{C}$ )	$I_O$	2.0	A
Peak Repetitive Forward Current (At Rated $V_R$ , Square Wave, 100 kHz, $T_C = 105^\circ\text{C}$ )	$I_{FRM}$	3.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	75	A
Storage/Operating Case Temperature	$T_{stg}$ , $T_C$	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature	$T_J$	-55 to +125	$^\circ\text{C}$
Voltage Rate of Change (Rated $V_R$ , $T_J = 25^\circ\text{C}$ )	$dv/dt$	10,000	V/ $\mu\text{s}$



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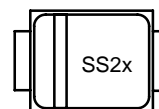
<http://onsemi.com>

**SCHOTTKY BARRIER  
RECTIFIER  
2 AMPERES  
20, 40 VOLTS**



**SMB  
CASE 403A  
PLASTIC**

### MARKING DIAGRAM



SS2x = Device Code  
x = 2 or 4

### ORDERING INFORMATION

Device	Package	Shipping
SS22T3	SMB	2500/Tape & Reel
SS24T3	SMB	2500/Tape & Reel

## SS22, SS24

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance — Junction-to-Lead (Note 1)	$R_{\theta JL}$	24	$^{\circ}\text{C}/\text{W}$
Thermal Resistance — Junction-to-Ambient (Note 2)	$R_{\theta JA}$	80	

### ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 3) see Figure 2 ( $i_F = 2.0 \text{ A}$ )	$v_F$	$T_J = 25^{\circ}\text{C}$	$T_J = 125^{\circ}\text{C}$	Volts
		0.50	0.46	
Maximum Instantaneous Reverse Current (Note 3) see Figure 4 ( $V_R = 40 \text{ V}$ )	$I_R$	$T_J = 25^{\circ}\text{C}$	$T_J = 100^{\circ}\text{C}$	mA
		0.4	5.7	

1. Mounted with minimum recommended pad size, PC Board FR4.
2. 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.
3. Pulse Test: Pulse Width  $\leq 250 \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

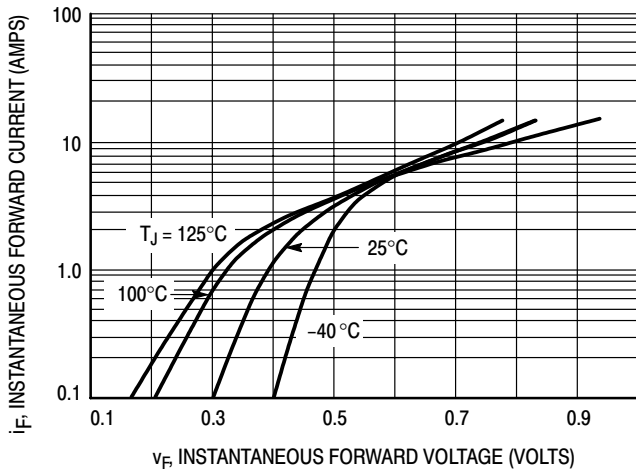


Figure 1. Typical Forward Voltage

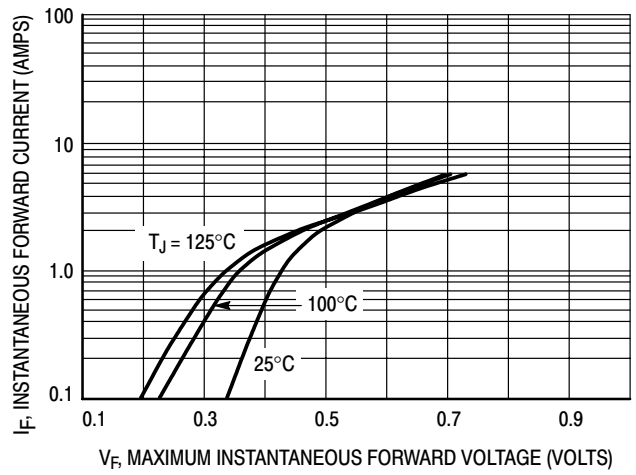


Figure 2. Maximum Forward Voltage

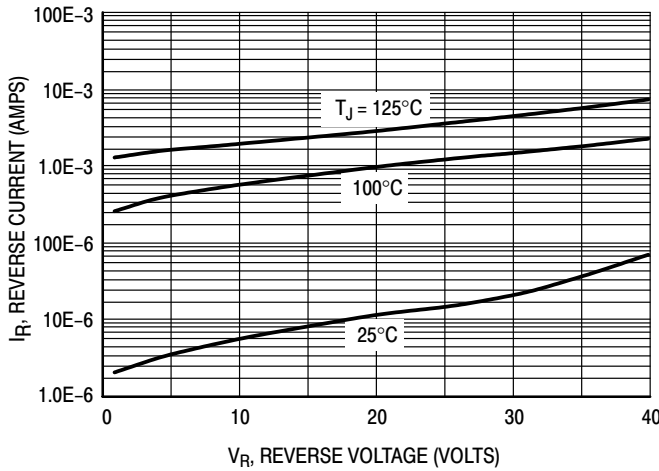


Figure 3. Typical Reverse Current

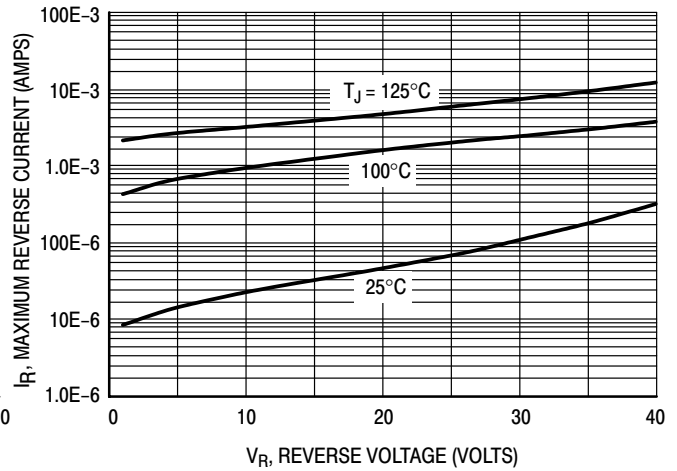


Figure 4. Maximum Reverse Current

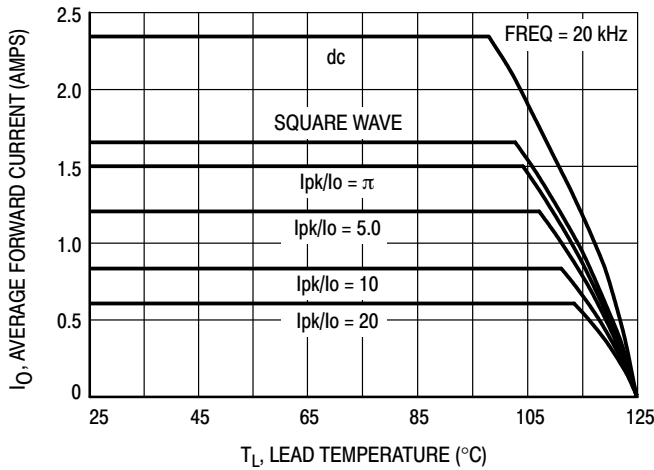


Figure 5. Current Derating

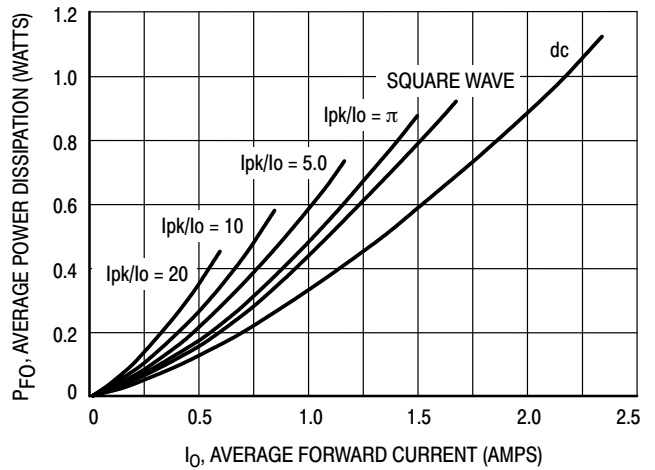
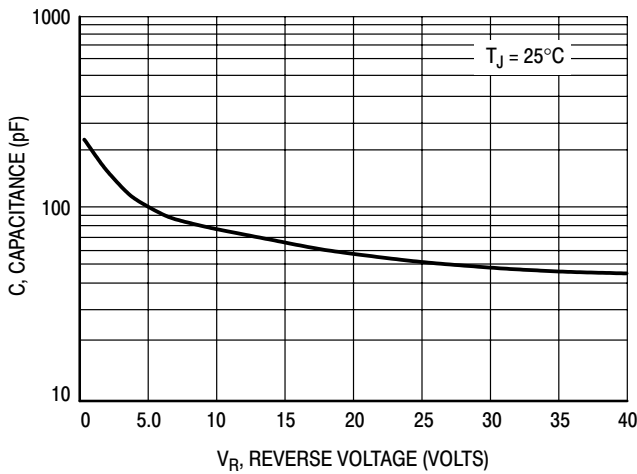
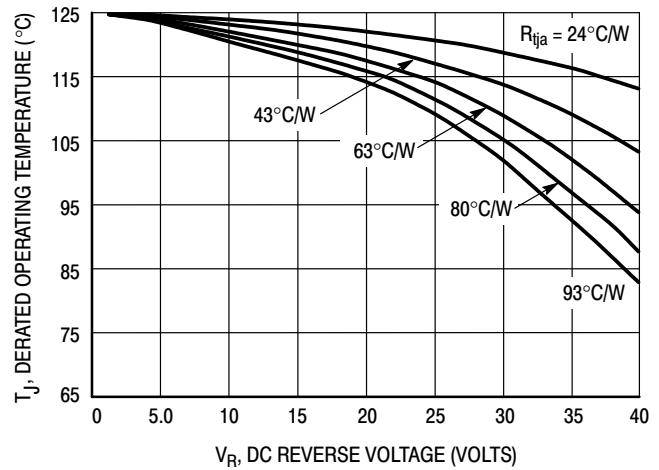


Figure 6. Forward Power Dissipation

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**Figure 7. Capacitance**



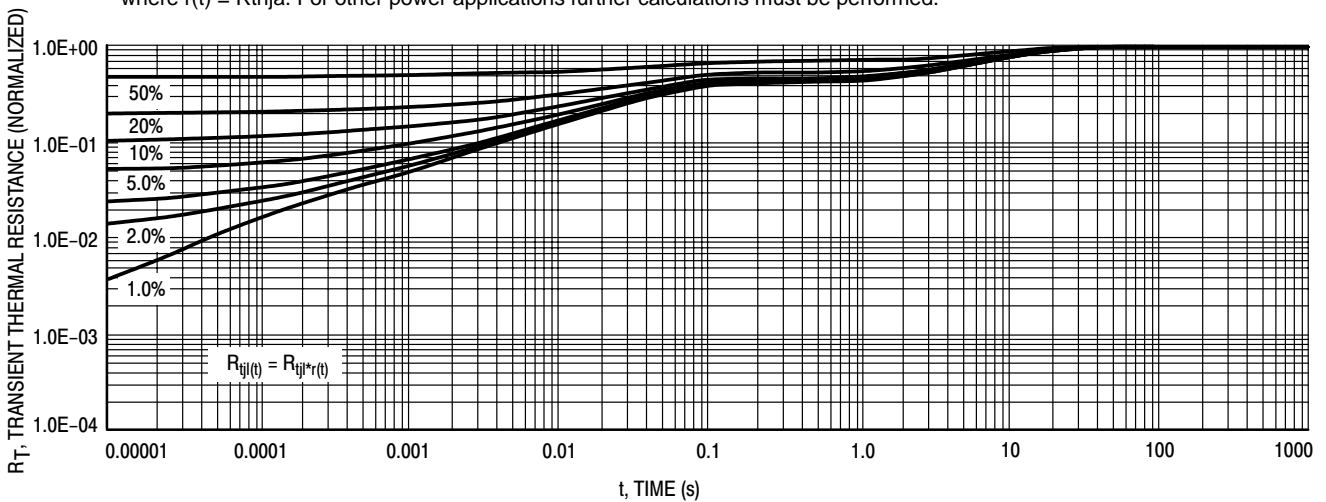
**Figure 8. Typical Operating Temperature Derating\***

\* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of  $T_J$  therefore must include forward and reverse power effects. The allowable operating  $T_J$  may be calculated from the equation:

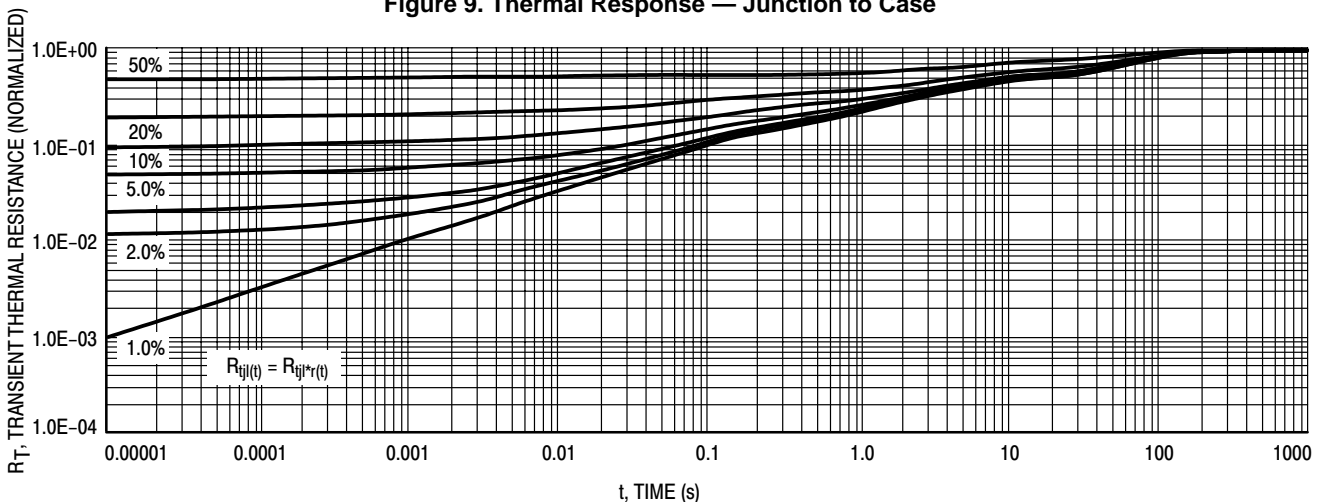
$$T_J = T_{Jmax} - r(t)(P_f + P_r) \text{ where}$$

$r(t)$  = thermal impedance under given conditions,  
 $P_f$  = forward power dissipation, and  
 $P_r$  = reverse power dissipation

This graph displays the derated allowable  $T_J$  due to reverse bias under DC conditions only and is calculated as  $T_J = T_{Jmax} - r(t)P_r$ , where  $r(t) = R_{thja}$ . For other power applications further calculations must be performed.



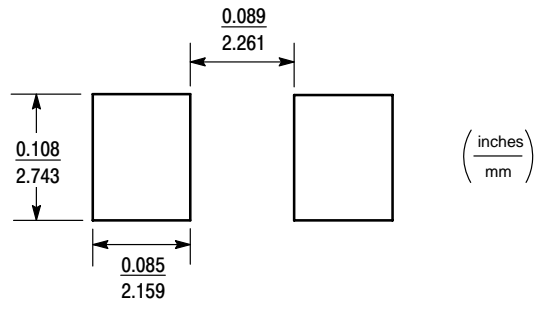
**Figure 9. Thermal Response — Junction to Case**



**Figure 10. Thermal Response — Junction to Ambient**

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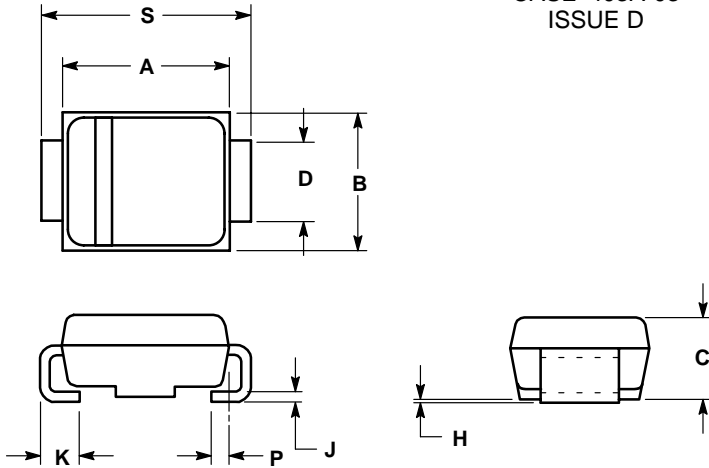
## MINIMUM SOLDER PAD SIZES



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## PACKAGE DIMENSIONS


### SMB PLASTIC PACKAGE CASE 403A-03 ISSUE D



#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.160	0.180	4.06	4.57
B	0.130	0.150	3.30	3.81
C	0.075	0.095	1.90	2.41
D	0.077	0.083	1.96	2.11
H	0.0020	0.0060	0.051	0.152
J	0.006	0.012	0.15	0.30
K	0.030	0.050	0.76	1.27
P	0.020 REF		0.51 REF	
S	0.205	0.220	5.21	5.59

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